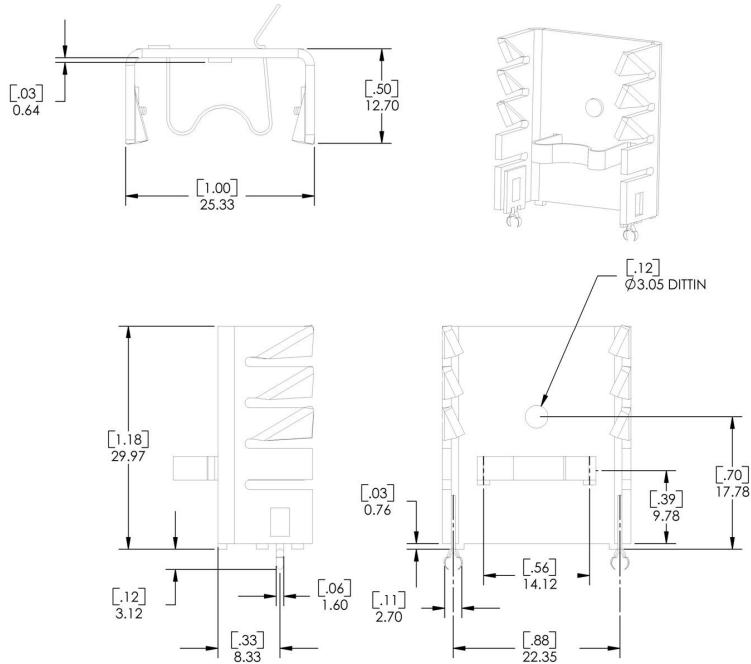
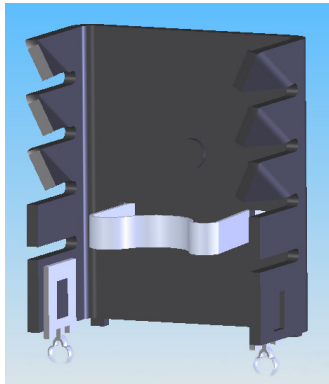


Board Level Heat Sinks



P/N: 825502B02853



PRODUCT SPECIFICATIONS

- Devices: TO-220
- Size: 25.4 x 12.7 x 30.0 mm
- Material: Aluminum, 1.2 mm Thick
- Type: Stamped
- IC Mounting: Integrated Spring
- PCB Mounting: Solderable Tabs
- Finish: Black Anodized
- Package: Bulk
- Optional Hardware: Thermal Interface Material

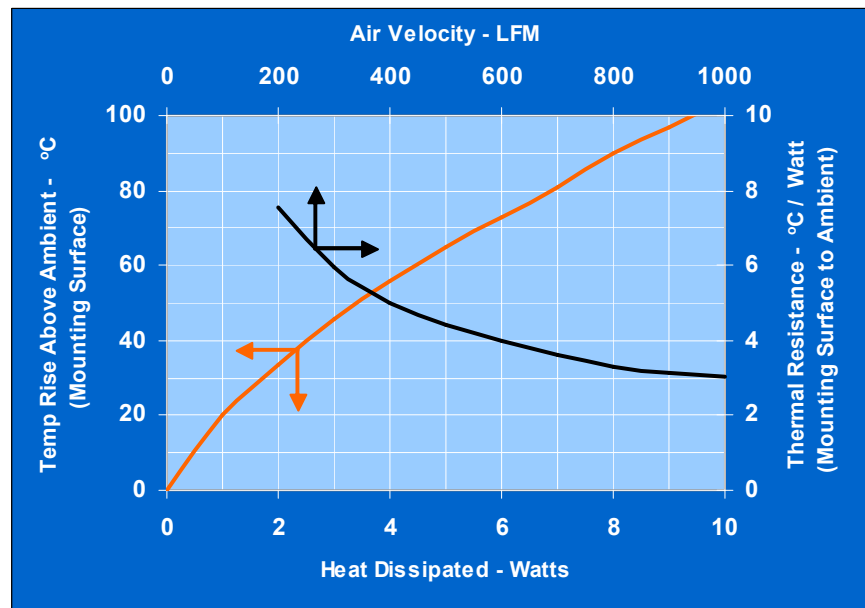
FEATURES & BENEFITS

- Spring Clip for Quick Device Attachment
- Curled Flow Fins
- Vertical Mounting via Solderable Tabs
- RoHS Compliant



CUSTOMIZED HEATSINKS

- Specialized Tabs, Plating
- Specialized Body Configurations
- Contact Applications Engineering



TO-220

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